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DBs: USPAT, US-PCPUB, EPO, JPO

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|----|--------------------------|--------------------------|-------------------|------------|-------|--|------------|---------------------------|--|
| 1 | <input type="checkbox"/> | <input type="checkbox"/> | US 20040101991 A1 | 20040527 | 13 | Microelectronic device packages and methods for controlling the disposition of | 438/106 | | |
| 2 | <input type="checkbox"/> | <input type="checkbox"/> | US 20040005732 A1 | 20040108 | 14 | MICROELECTRONIC DEVICE PACKAGES AND METHODS FOR CONTROLLING THE | 438/105 | | |
| 3 | <input type="checkbox"/> | <input type="checkbox"/> | US 20030189262 A1 | 20031009 | 17 | Method and apparatus for attaching microelectronic substrates and support | 257/783 | 257/784 | |
| 4 | <input type="checkbox"/> | <input type="checkbox"/> | US 20030116861 A1 | 20030626 | 18 | Multi-substrate microelectronic packages and methods for manufacture | 257/778 | 257/E21.512; 257/E25.013 | |
| 5 | <input type="checkbox"/> | <input type="checkbox"/> | US 20030100200 A1 | 20030529 | 15 | Buried solder bumps for AC-coupled microelectronic interconnects | 439/56 | | |
| 6 | <input type="checkbox"/> | <input type="checkbox"/> | US 20030012868 A1 | 20030116 | 15 | Method for dispensing flowable substances on microelectronic substrates | 427/8 | 427/58 | |
| 7 | <input type="checkbox"/> | <input type="checkbox"/> | US 20020190396 A1 | 20021219 | 13 | Method and apparatus for removing encapsulating material from a packaged | 257/787 | 257/686; 257/713; | |
| 8 | <input type="checkbox"/> | <input type="checkbox"/> | US 20020020898 A1 | 20020221 | 35 | Microelectronic substrates with integrated devices | 257/676 | 257/668; 257/701, | |
| 9 | <input type="checkbox"/> | <input type="checkbox"/> | US 20010008357 A1 | 20010719 | 17 | Methods of fabricating in-plane MEMS thermal actuators | 310/306 | | |
| 10 | <input type="checkbox"/> | <input type="checkbox"/> | US 6750547 B2 | 20040615 | 15 | Multi-substrate microelectronic packages and methods for manufacture | 257/778 | 257/E21.508; 257/E23.069; | |
| 11 | <input type="checkbox"/> | <input type="checkbox"/> | US 6680079 B2 | 20040120 | 15 | Method for dispensing flowable substances | 427/8 | 118/320; 118/321 | |